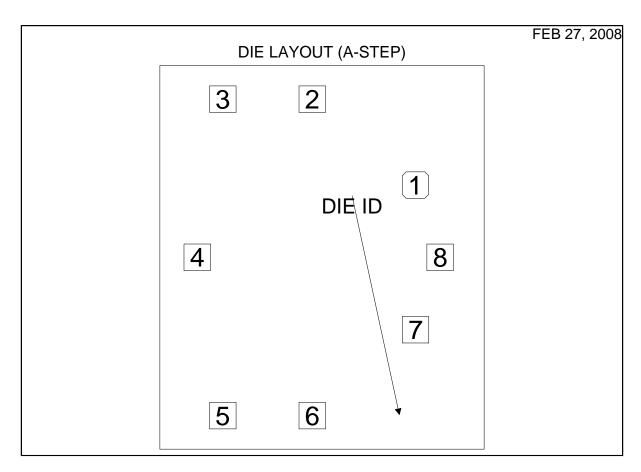


## LMH6715 MDC MWC DUAL WIDEBAND VIDEO OP AMP



### DIE/WAFER CHARACTERISTICS

DIE/WAFER CHARA	CIERISTICS				
Fabrication Attributes		General Die Information			
Physical Die	LMH6715A	Bond Pad Opening	77.00µm x 77.00µm		
Identification		Size (min)			
Die Step	A	Bond Pad Metalization	AL 0.5%CU		
Physical Attributes		Passivation	PECVDOX NITRIDE		
Wafer Diameter	150µm	Back Side Metal	BAREBACK		
Die Size (Drawn)	942µm x 1115µm 37.1mils x 43.9mils	Back Side Connection	Floating		
Thickness	254µm Nominal				
Min Pitch	210µm				
Note: All values are round	ded to the nearest micron				
Special Assembly Requir	ements:				



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Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		Χ	Υ	Χ		Υ
V out 1	1	271	209	77	Х	77
V inv 1	2	-28	459	77	Х	77
V non-inv 1	3	-288	459	77	Х	77
- VCC	4	-362	0	77	Х	77
V non-inv 2	5	-288	-460	77	Х	77
V inv 2	6	-28	-460	77	Х	77
V out 2	7	271	-210	77	Х	77
+ VCC	8	343	0	77	Х	77



# LMH6715 MDC MWC DUAL WIDEBAND VIDEO OP AMP

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